Overview

KC-LINK™ with KONNEKT™ technology surface mount capacitors are designed for high-efficiency and high-density power applications. KONNEKT high density packaging technology uses an innovative Transient Liquid Phase Sintering (TLPS) material to create a surface mount multi-chip solution for high density packaging.

Construction

- Ceramic dielectric
- Electrode plate
- CuSn TLPS
- Cu termination
- Sn termination finish

Benefits

- Stable capacitance with temperature, frequency, and voltage
- Ultra-low ESR: < 2.5 mΩ
- Ultra-low ESL: 0.45 nH
- Surface mount capable with standard reflow
- No piezoelectric noise

Electrical Characteristics

- Operating Temperature: −55°C to +150°C
- Rated Capacitance: 44 nF – 880 nF (±10% tol.)
- Typical ESR at 100 kHz: < 2.5 mΩ max
- Rated Voltage: 500 V – 1,700 V

KC-LINK with KONNEKT Selection Guide

<table>
<thead>
<tr>
<th>Capacitance (nF)</th>
<th>Rated Voltage (V)</th>
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</thead>
<tbody>
<tr>
<td>44</td>
<td>500 – 1,700</td>
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<tr>
<td>88</td>
<td>500 – 1,700</td>
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<td>128</td>
<td>500 – 1,700</td>
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<td>220</td>
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<td>336</td>
<td>500 – 1,700</td>
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<tr>
<td>500</td>
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<tr>
<td>880</td>
<td>500 – 1,700</td>
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</tbody>
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Part Number System

- CKC
- 33
- 884
- K
- C
- G
- L
- C

- Termination – C: 100% Sn
- Subclass – L: KONNEKT
- Dielectric – G: C0G
- Rated Voltage – C: 500 V
- Tolerance code – K: 10%
- Cap Code – 884: 88x10^4 pF
- Specification – C: Standard
- Case Size – 33: 3640

https://ec.kemet.com/konnekt